

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 15.10L x 13.00W x 1.30H mm  
 Weight: Approx. 0.23 g  
 Contact principle: Friction technology  
 Operating position: Shaft up / Down / Horizontal  
 Mounting System: SMT Type (without post)  
 Function: Push Pull Type  
 Durability: 5,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0  
 RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

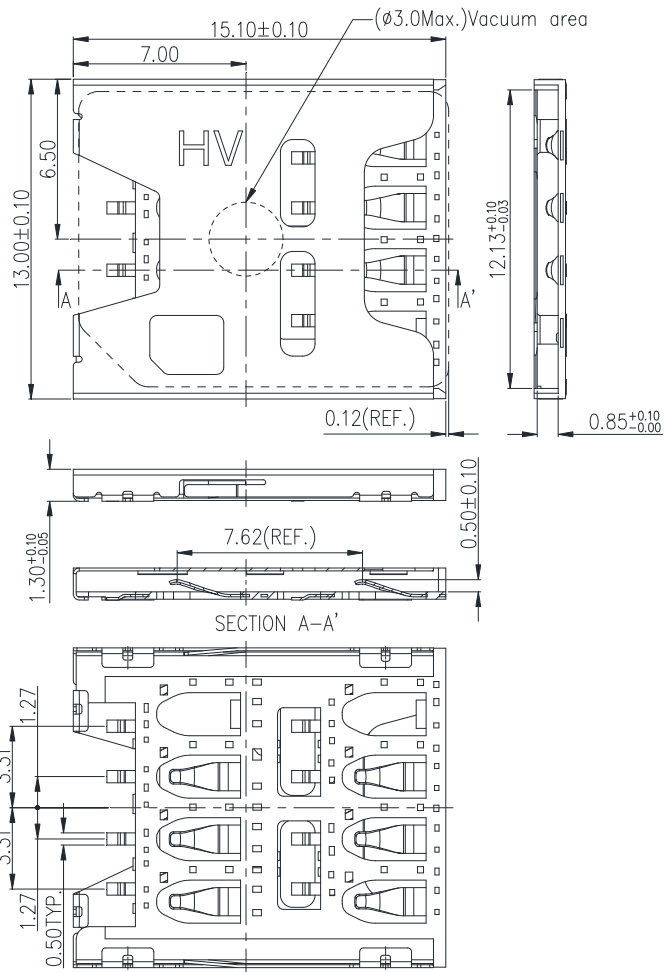
Number of contacts: 6, 8 pins (optional)  
 Contact resistance: 50 mΩ typical, 100 mΩ max.  
 Insulation resistance: >1000 MΩ / 500 VDC

### 4. Solderability

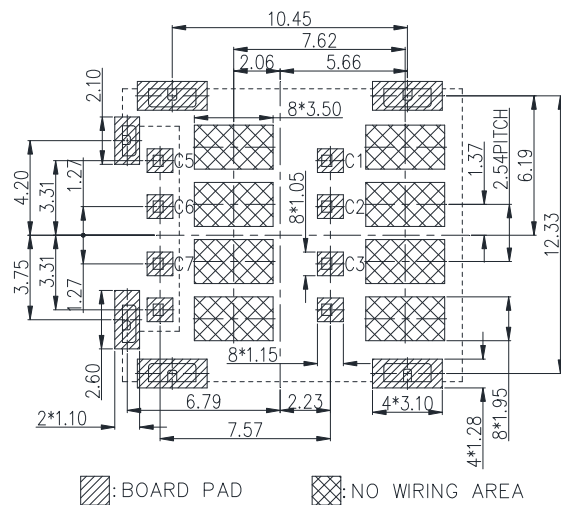
Wave: Not applicable  
 IR reflow: 260°C, 10 sec. Max.  
 Manual soldering: 360°C, 3 sec. Max.

### 5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C  
 Operating humidity: 10 % ~ 95 % RH  
 Storage temperature: - 40°C ~ + 85°C  
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm  
 Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm  
 Reference dimension for PCB layout

H&V Micro SIM Card Connector

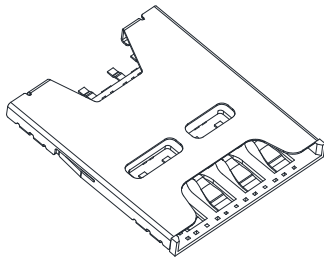
Model No.: ICC-M06 6Pin

Revision: 1.0

Date: MAY 01, 2014

#### Note:

- Coplanarity of solder pins 0.10mm max.
- Recommended thickness of solder paste > 0.15mm.



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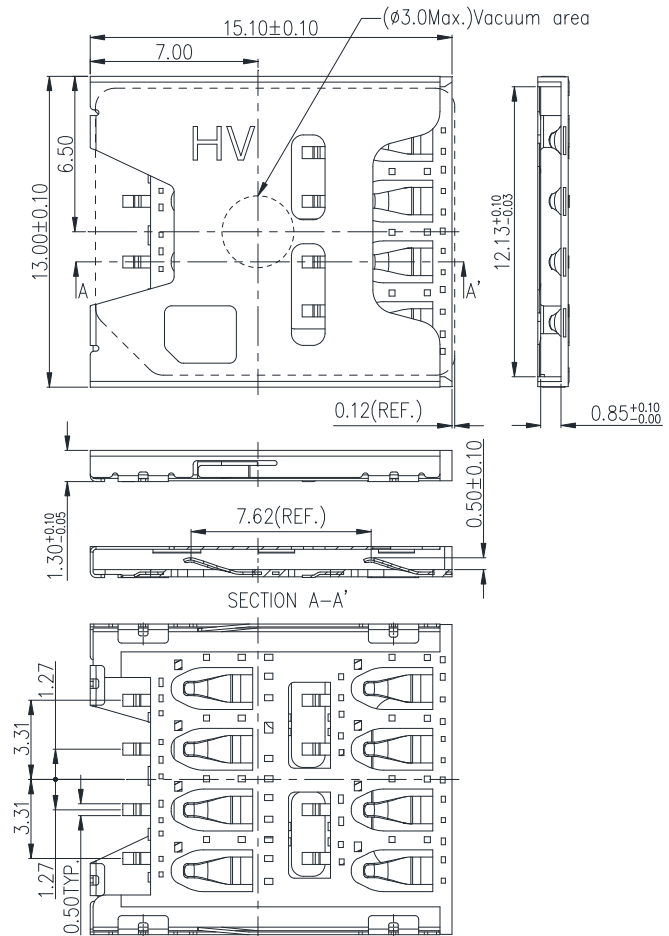
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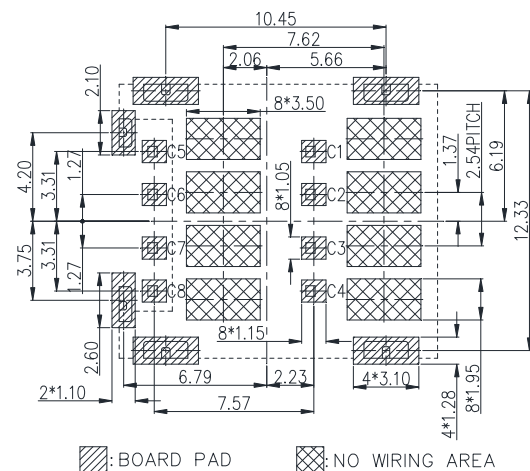
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**Mechanical outline dimension**



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**Reference dimension for PCB layout**

H&V Micro SIM Card Connector

Model No.: ICC-M06 8Pin

Revision: 1.0

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#### Note:

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2. Recommended thickness of solder paste > 0.15mm.